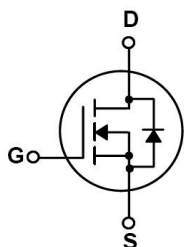


/ Descriptions

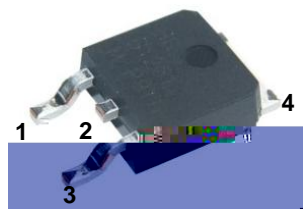
/ Features

/ Applications

/ Equivalent Circuit

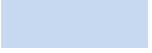


/ Pinning

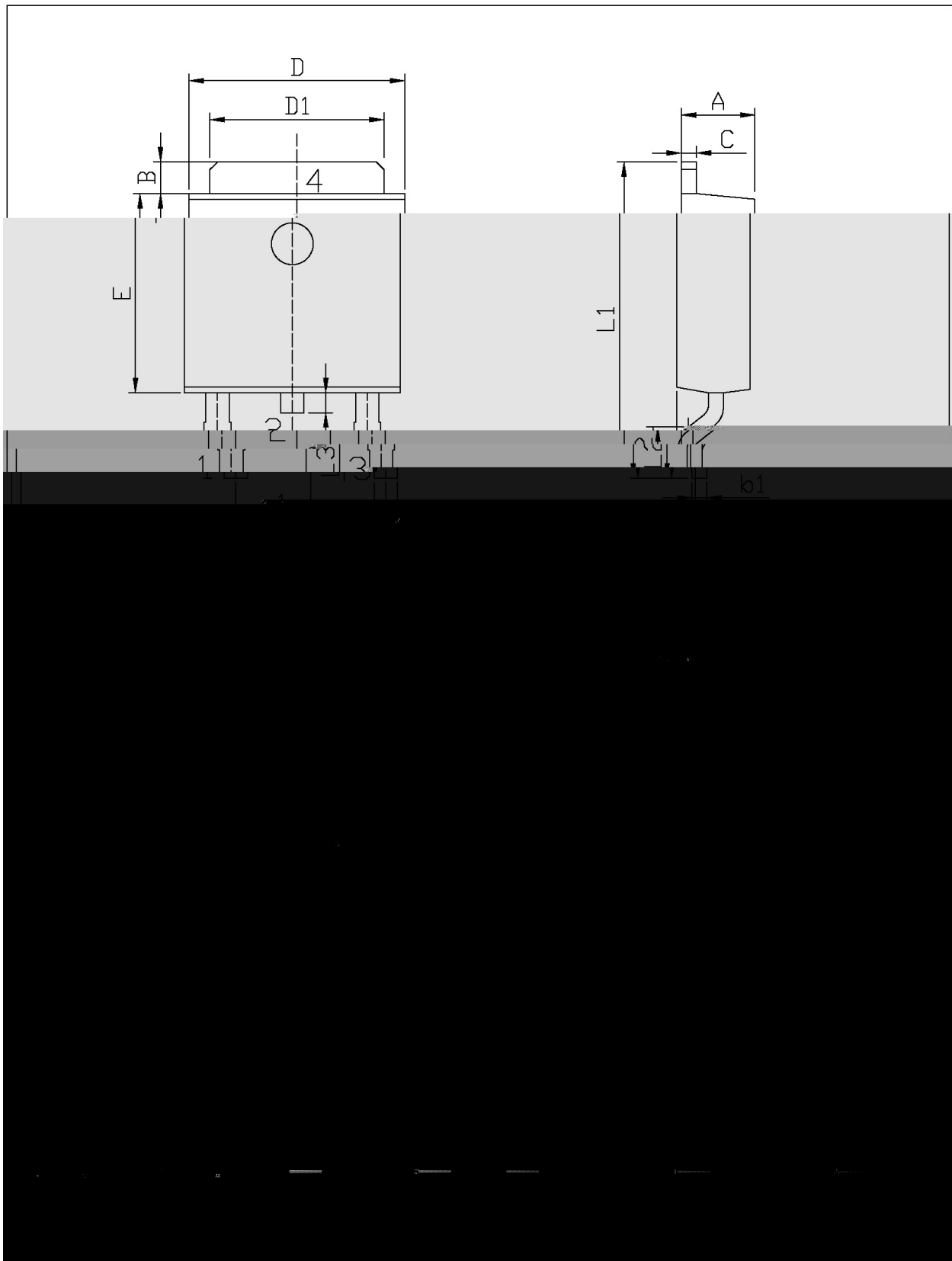


/ h_{FE} Classifications & Marking

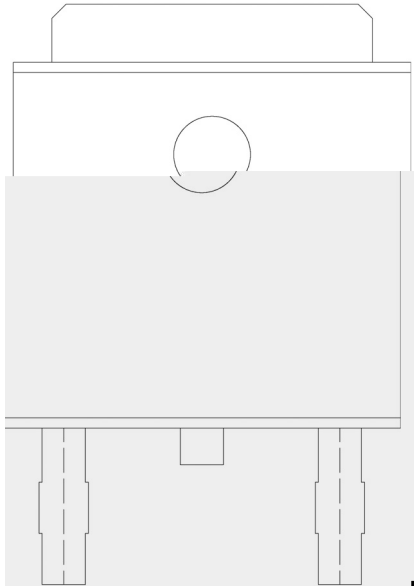
BRD4N



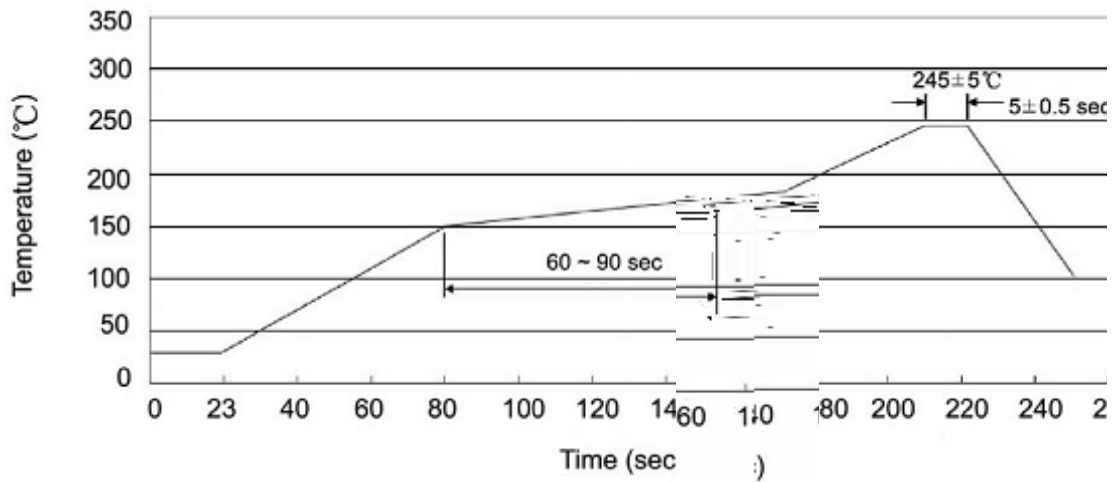
/ Package Dimensions



/ Marking Instructions



() / Temperature Profile for Dip Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ±

/ Packaging SPEC.

封装形式	包装数量					包装尺寸		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	
TO-252	2,500	2	5,000	5	25,000	13 ×16	360×360×50	

封装形式	包装数量					包装尺寸		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	
TO-251/252	75	48	3,600	5	18,000	526×20.5×5.25	555×164×50	

/ Notices